On-chip Inductance Modeling and RLC Extraction of VLSI Interconnects for Circuit Simulation

Xiaoning Qi, G. Wang, Z. Yu, R. Dutton Stanford University

T. Young Synopsys Inc.

N. Chang HP Labs, Palo Alto

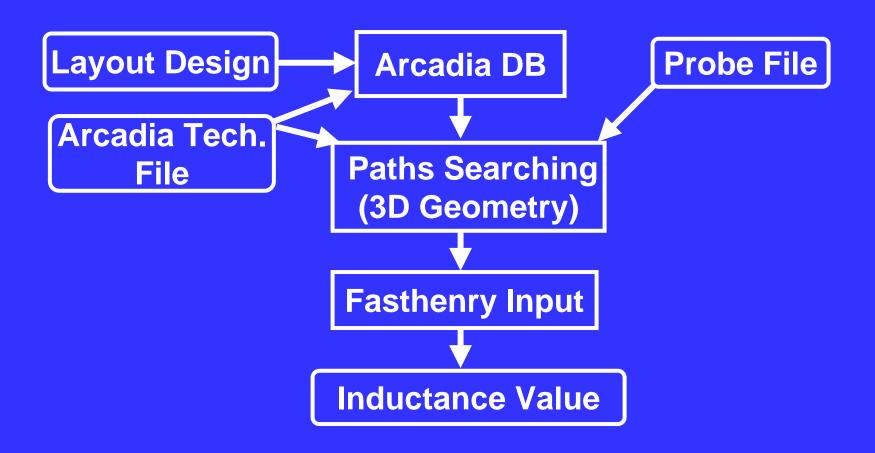
Outline

- Background and motivation
- 3D geometry modeling and inductance extraction using field solvers
- Analytical formulae for inductance estimation
- Applications in circuit simulation
- Summary

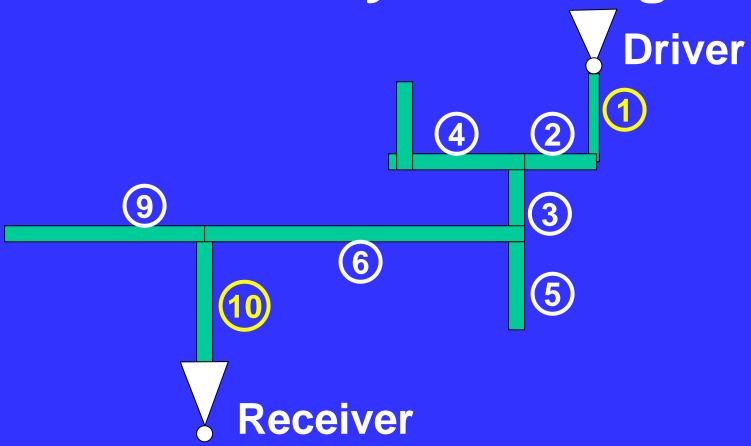
Background and Motivation

- Long wires exhibit transmission line effects with faster transistor rise/fall time.
- Inductance component becomes comparable to resistance component.
- Signal ringing and inductive cross talk are observed. Ground bounce becomes worse.

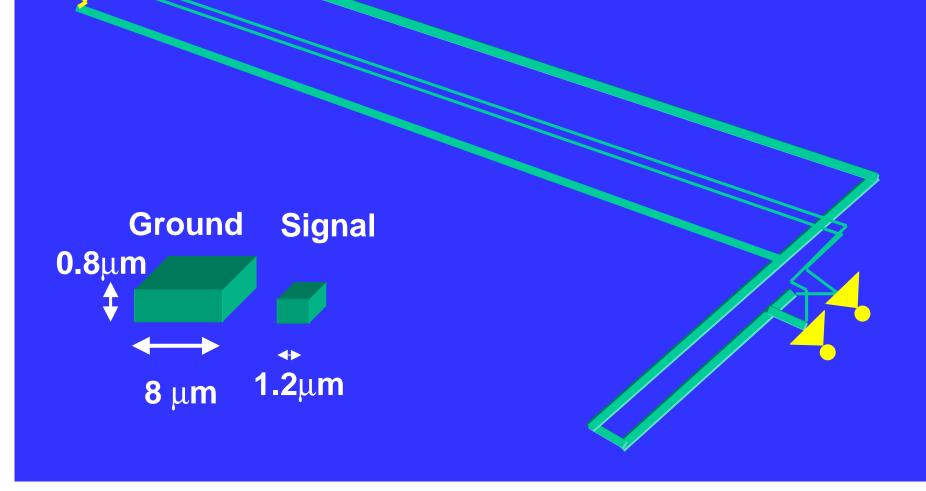
3D Geometry Modeling for Field Solver



Path Searching in 3D Geometry Modeling

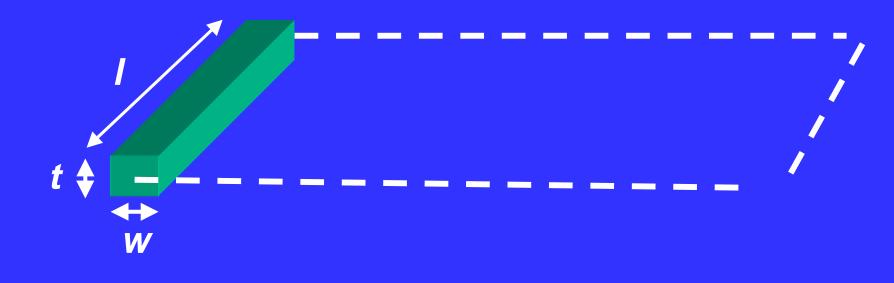


Extracted 3D Geometry



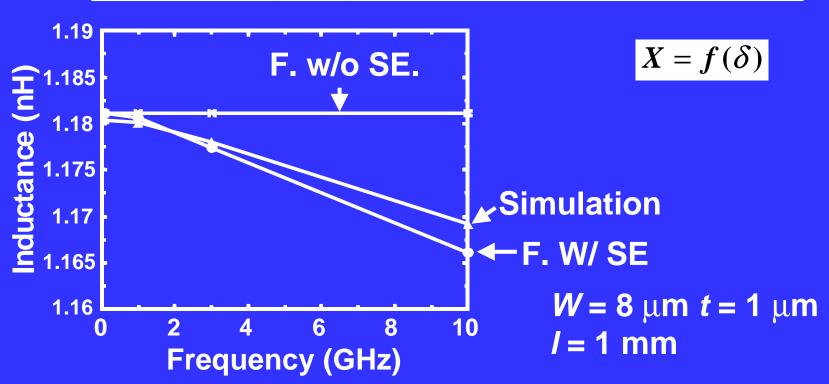
Self-inductance Formula

$$L_{self} = \frac{\mu o l}{2\pi} \left[\ln(\frac{2l}{w+t}) + \frac{1}{2} + \frac{0.447(w+t)}{2l} \right]$$



Self-inductance With Skin Effect

$$L_{self} = \frac{\mu_0 l}{2\pi} \left[\ln \left(\frac{2l}{w+t} \right) + \frac{1}{2} + \frac{0.2235(w+t)}{l} - \mu_r (0.25 - X) \right]$$

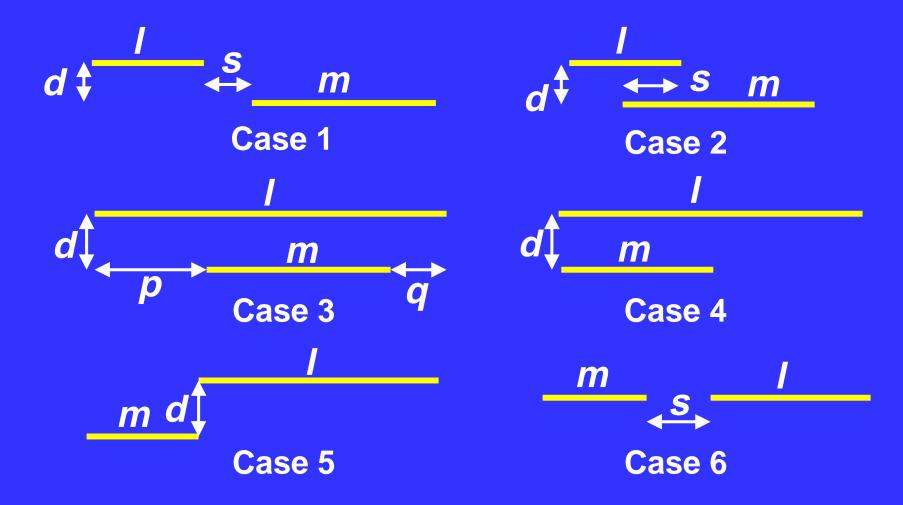


Mutual Inductance

$$M = \frac{\mu \, ol}{2\pi} \left[\ln \left(\frac{2l}{d} \right) - 1 + \frac{d}{l} \right]$$



Six Different Positions



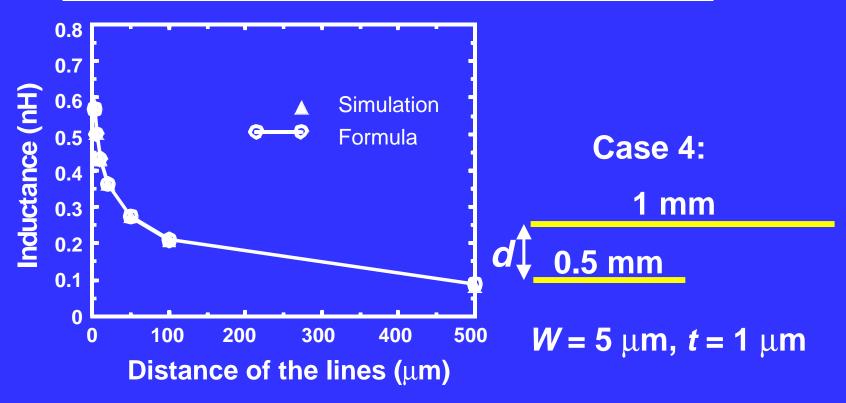
Calculating Mutual Inductance

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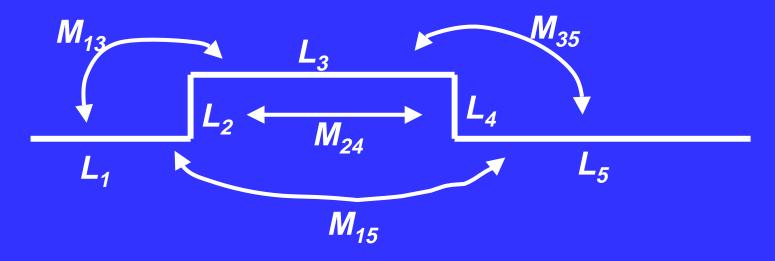
$$M = \frac{1}{2}[(M_{m+p} + M_{m+q}) - (M_p + M_q)]$$

Formula and Simulation

$$M = \frac{\mu_0}{4\pi} \left[l \ln\left(\frac{l}{l-m}\right) + m \ln\left(\frac{4m(l-m)}{d^2}\right) - 2m + d \right]$$



Self Inductance of a Whole Wire



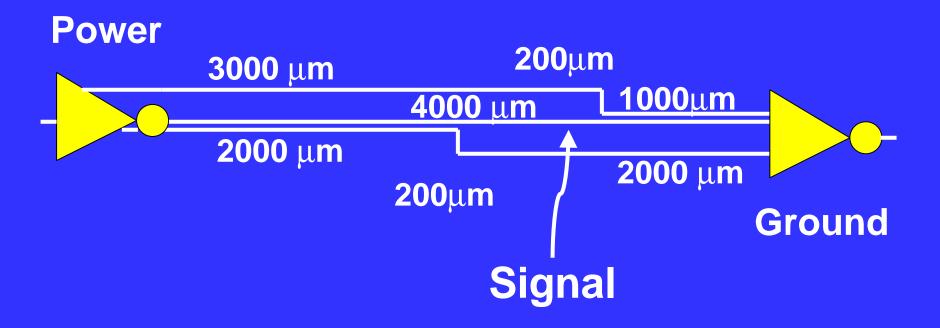
$$L_{total} = \sum_{i=1}^{5} L_i + 2M_{13} + 2M_{15} + 2M_{24} + 2M_{35}$$

Formula and Simulation of Self Inductance

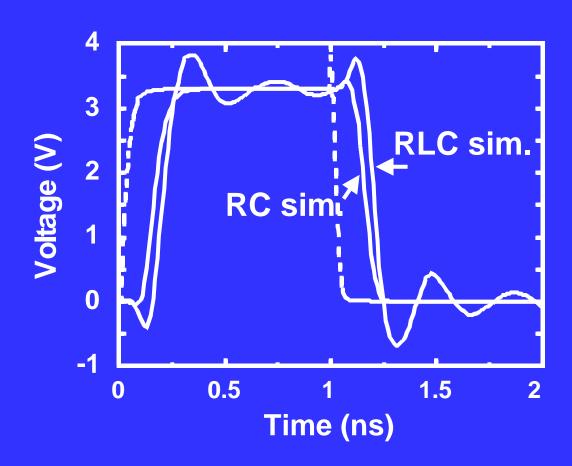
Inductance Unit: nH

segments, 3			Segments, 4			Wire3: 5 Segments, 5 turns (4 mm)		
Sim.	Cal.	Err.	Sim.	Cal.	Err.	Sim.	Cal.	Err.
2.27	2.26	0.4%	2.93	2.86	2.3%	5.35	5.17	3.4%

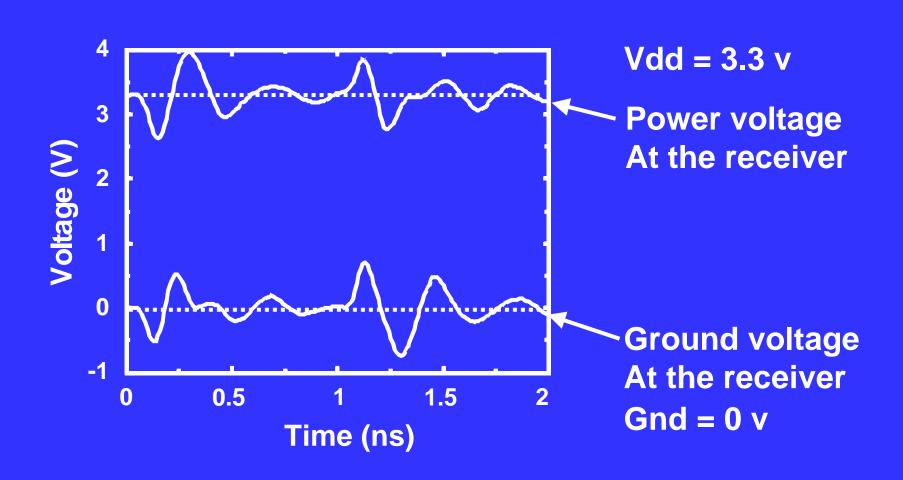
One Global Line Example



Signal Ringing Effects



Power and Ground Noise



Summary

- Accurate automatic 3D geometry generation
- Analytical formulae for self and mutual inductance estimation
- Impact of on-chip inductance on signal integrity and power/ground noise